



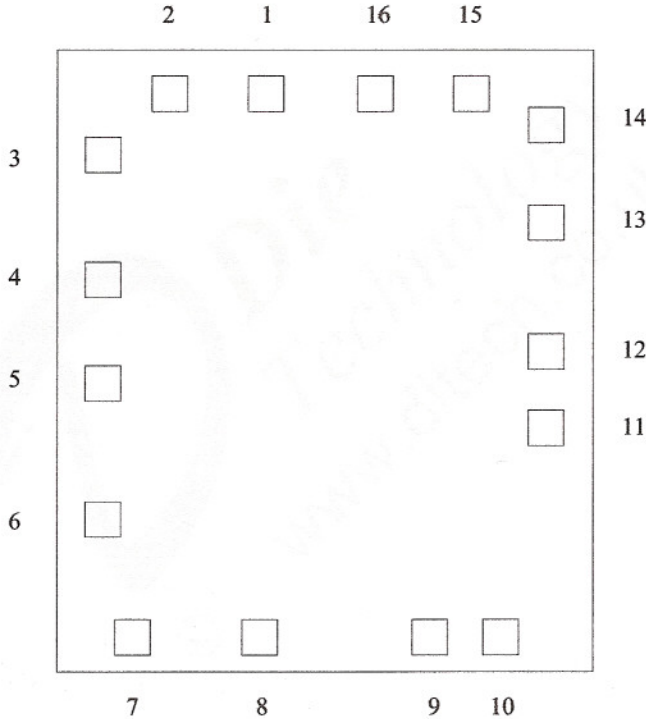
Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

PAD FUNCTIONS

- 1 A0
- 2 A1
- 3 A2
- 4 Q0
- 5 Q1
- 6 Q2
- 7 Q3
- 8 GND
- 9 Q4
- 10 Q5
- 11 Q6
- 12 Q7
- 13 D
- 14 NOT LE
- 15 NOT MR
- 16 Vcc



NOTE: FIRST BOND TO PAD # 16

The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

<u>APPROVED</u> GB DATE: 22/06/2007	<h2>54HC259</h2> <h3>TEXAS INSTRUMENTS</h3>	<u>DIE INFORMATION</u> DIMENSIONS (Mils): 68 x 90 x 25 BOND PADS (Mils): 3.6 x 3.6 MASK REF: GEOMETRY: HC259E BACK CONNECTION: FLOATING or tie to Vcc
<u>SERIAL NUMBER</u> 008713		<u>METALLISATION</u> TOP: Al BACK: Si